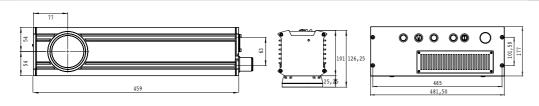
F Duo Series



								F - I	0U0 S	eries	& M0P	Α								
MODEL					PULSED & PULSED UHS												MOPA			
POWER			1	0W	20	OW		30W		51)W		100W			20W	50W			
WAVELENGTH			1.062 µm																	
FREQUENCY			25-100Kh ²													Ø-1000Kh2				
PULSE WIDTH				100ns												8 selectable 4-200ns				
LASER SYSTEM			PUL	-10 SED & ED UHS	F - 20 PULSED & PULSED UHS		F - 30 PULSED & PULSED UHS		F - 50 PULSED & PULSED UHS		F - 100 PULSED & PULSED UHS			F - 20 MOPA		F - 50 MOPA				
MAINS SUPPLY				50 / (1 Pha	- 240V 60 Hz ase + N)	100V - 240V 50 / 60 Hz (1 Phase + N) 350 VA		100V - 240V 50 / 60 Hz (1 Phase + N) 400 VA		100V - 240V 50 / 60 Hz (1 Phase + N) 600 VA		100V - 240V 50 / 60 Hz (1 Phase + N) 750 VA			100V - 240V 50 / 60 Hz (1 Phase + N) 350 VA		100V - 24 50 / 60 H (1 Phase + 600 VA	Hz + N)		
Head Head				108x106.5x469 mm 115x98							98x463 mm			108x106.5x469 mm		115x98x463	3 mm			
DIMENSIONS Rack				464x177x550 mm																
WEIGHT				Net weight: 23Kg - Gross Weight: 27Kg												Net weight: 23Kg - Gross Weight: 27Kg				
	SYSTEM						or of the la						to the ma	arking he	ead. Cont	trol and po	ower electronic	s, drivers of the	•	
	TEOLINGLOOV			PULSED PULSED UHS										МОРА						
FOCAL SPECIFIC.	TECHNOLOGY			F-	10	20	30	50	100	F-	10	20	30	50	100	F-	20	50)	
	MA (mm)	WD (mm)	FL (mm)	BD (µm)	PD (KW/ cm²)	PD (KW/ cm²)	PD (KW/ cm²)	PD (KW/ cm²)	PD (KW/ cm2	BD (µm)	PD (KW/ cm²)	PD (KW/ cm²)	PD (KW/ cm²)	PD (KW/ cm²)	PD (KW/ cm2)	BD (µm)	PD (KW/ cm²)	P[(KV cm	N/	
	55x55	141	100	16	9709	19417	29126	48542	97085	27	3482	6964	10446	17409	34819	16	19417	485		
	100x100	205	163	26	3654	7308	10962	18270	36540	44	1327	2653	3980	6634	13267	26	7308	182	70	
	168x168	347	254	41	1505	3009	4514	7524	15045	69	540	1079	1619	2698	5397	41	3009	752	24	
	212x212	458	346	56	811	1622	2433	4054	8110	94	291	582	873	1454	2908	56	1622	405	54	
	242x242	554	420	68	551	1101	1652	2752	5505	-	-	-	-	-	-	68	1101	275	52	
	560x560	888,5	815	132	146	292	438	731	1460	-	-	-	-	-	-	132	292	73	1	
	LEGEND IMPORTANT NOTE			WD:Working Distance FL:Focal Length MA:Marking Area BD: Spot Beam Diameter PD:Power Density - Working Distance (WD): The distance between the laser system base and the surface to be marked. - Focal Length (FL): The distance between the center of the lens and the surface to be marked. - Approximate values: These values are an approximation, and they are different for each laser system, due to the different optical paths.																
SOFTWARE				ScanLinux (Standard). Crystal Font (Standard). Internal Barcode. Marca Lite Software.																
USER INTERFACE				Touch Screen. Hand Held Terminal. PC.																
CONTROLLED BY				 Hand Held Terminal with ScanLinux software. Touch Screen with ScanLinux software. Full Graphics Interface: includes Marca™ software, dongle and Ethernet cable (TCP / IP). Marca Lite Software: includes Marca™ software, dongle and Ethernet cable (TCP / IP). 																
ACCESSORIES				Handheld Terminal-Touch Screen Terminal - Beam pointer - Encoder Kit - Photocell Kit - Alarm Kit - Fume Extractor - Mounting support - Mounting Bracket U-ARM - Marking paper - Protection goggles - Air Cooling Kit																
ENVIRONMENTAL CONDITIONS					Humidity be		external t % and 95%				ity Cycle o	r 36°C(100	0°F) exte	rnal tem	perature	with 1009	% Duty			

^{*} approximate data that may have small variations in reality





Coding, tracing and marking solutions worldwide







F DUO Series

INDUSTRIAL FIBER LASER

High precision 2D and 3D marking on metals











F DUO Series by MACSA

Powerful. Reliable. Precise.

INDUSTRIAL FIBER LASER

F DUO Series

A family of powerful and reliable industrial fibre lasers.

F DUO lasers are designed for high-speed on-line integration and for use in standalone workstations.

They are ideal for demanding metal marking applications, but are also effective with other materials such as plastics and composite materials.

F DUO lasers are long life, low maintenance lasers with very low cost of ownership.

The F DUO pulsed fiber laser product range has been extended to include MOPA lasers.







F MOPA

For high precision marking

MOPA technology allows the shape and duration of the waveform to be controlled and selected by the user in order to optimize the conditions for high precision marking and micro machining applications.

- Shorter pulse widths are ideal for marking delicate substrates such as plastics or thin materials. An extended frequency range enables higher repetition rates with shorter pulse widths to be used which leads to higher productivity.
- Longer pulse widths are ideal for deep engraving and other bulk material removal applications.

The key to high precision marking applications is precise thermal management and with 8 selectable and programmmable pulse withds. F MOPA laser is the perfect tool for those demanding, high value add applications.









Macsa lasers are very easy to use thanks to our powerful propietary marking software.

Marca makes it simple to code and mark precisely and consistenly. A userfriendly software to create text, 1D and 2D codes, 3D graphics, graphical files, etc...







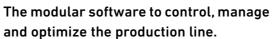














Solution of monitoring services, predictive maintenance, remote assistance and production support

3D marking

2D marks can be mapped to regular 3D geometries such as cylinders, spheres and cones. Additionally irregular geometries can be loaded as 3D CAD files in to Marca software enabling 2D marks to be mapped to irregular 3D surfaces. The Macsa 3D scan head greatly simplifies the mechanical handling of 3D geometries and can eliminate the need for rotary and robotic handling devices. This can significantly increase productivity.

DUO by Macsa

Dual Processor Technology Lasers by Macsa allows high precision marks to be produced even with variable data with no loss of performance. This technology dedicates one processor to data processing and the other to controlling the laser.

